

MC74LVX125

Quad Bus Buffer

With 5 V-Tolerant Inputs

The MC74LVX125 is an advanced high speed CMOS quad bus buffer. The inputs tolerate voltages up to 7.0 V, allowing the interface of 5.0 V systems to 3.0 V systems.

The MC74LVX125 requires the 3-state control input (\overline{OE}) to be set High to place the output into the high impedance state.

Features

- High Speed: $t_{PD} = 4.4$ ns (Typ) at $V_{CC} = 3.3$ V
- Low Power Dissipation: $I_{CC} = 4$ μ A (Max) at $T_A = 25^\circ\text{C}$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Low Noise: $V_{OLP} = 0.5$ V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance: Human Body Model > 2000 V
Machine Model > 200 V
- These Devices are Pb-Free and are RoHS Compliant

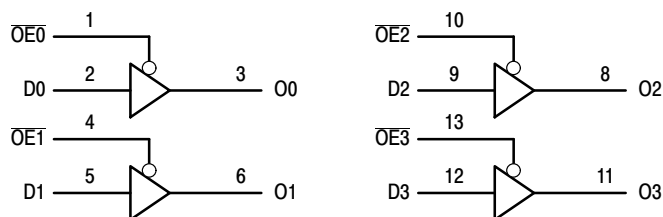


Figure 1. Logic Diagram

PIN NAMES

| Pins | Function |
|-------------------|----------------------|
| \overline{OE}_n | Output Enable Inputs |
| D_n | Data Inputs |
| O_n | 3-State Outputs |

FUNCTION TABLE

| INPUTS | | OUTPUTS |
|-------------------|-------|---------|
| \overline{OE}_n | D_n | O_n |
| L | L | L |
| L | H | H |
| H | X | Z |

H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; X = High or Low Voltage Level and Transitions Are Acceptable, for I_{CC} reasons, DO NOT FLOAT Inputs



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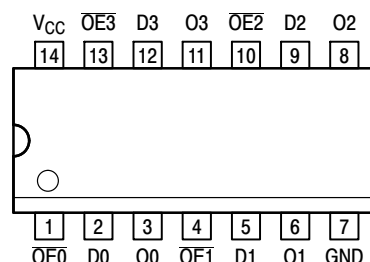


SOIC-14 NB
D SUFFIX
CASE 751A



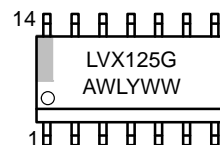
TSSOP-14
DT SUFFIX
CASE 948G

PIN ASSIGNMENT

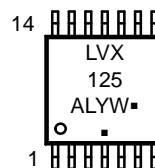


14-Lead (Top View)

MARKING DIAGRAMS



SOIC-14 NB



TSSOP-14

LVX125 = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MC74LVX125

MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|-----------|--|-----------------------|------|
| V_{CC} | DC Supply Voltage | −0.5 to +7.0 | V |
| V_{in} | DC Input Voltage | −0.5 to +7.0 | V |
| V_{out} | DC Output Voltage | −0.5 to V_{CC} +0.5 | V |
| I_{IK} | Input Diode Current | −20 | mA |
| I_{OK} | Output Diode Current | ±20 | mA |
| I_{out} | DC Output Current, per Pin | ±25 | mA |
| I_{CC} | DC Supply Current, V_{CC} and GND Pins | ±50 | mA |
| P_D | Power Dissipation | 180 | mW |
| T_{stg} | Storage Temperature | −65 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|---------------------|--|-----|----------|------|
| V_{CC} | DC Supply Voltage | 2.0 | 3.6 | V |
| V_{in} | DC Input Voltage | 0 | 5.5 | V |
| V_{out} | DC Output Voltage | 0 | V_{CC} | V |
| T_A | Operating Temperature, All Package Types | −40 | +85 | °C |
| $\Delta t/\Delta V$ | Input Rise and Fall Time | 0 | 100 | ns/V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Test Conditions | V_{CC} V | $T_A = 25^\circ\text{C}$ | | | $T_A = -40 \text{ to } 85^\circ\text{C}$ | | Unit |
|----------|--|--|-------------------|--------------------------|------------|--------------------|--|--------------------|------|
| | | | | Min | Typ | Max | Min | Max | |
| V_{IH} | High-Level Input Voltage | | 2.0 3.0 3.6 | 1.5 2.0 2.4 | | | 1.5 2.0 2.4 | | V |
| V_{IL} | Low-Level Input Voltage | | 2.0 3.0 3.6 | | | 0.5 0.8 0.8 | | 0.5 0.8 0.8 | V |
| V_{OH} | High-Level Output Voltage ($V_{in} = V_{IH}$ or V_{IL}) | $I_{OH} = -50\mu\text{A}$ $I_{OH} = -50\mu\text{A}$ $I_{OH} = -4\text{mA}$ | 2.0 3.0 3.0 | 1.9 2.9 2.58 | 2.0 3.0 | | 1.9 2.9 2.48 | | V |
| V_{OL} | Low-Level Output Voltage ($V_{in} = V_{IH}$ or V_{IL}) | $I_{OL} = 50\mu\text{A}$ $I_{OL} = 50\mu\text{A}$ $I_{OL} = 4\text{mA}$ | 2.0 3.0 3.0 | | 0.0 0.0 | 0.1 0.1 0.36 | | 0.1 0.1 0.44 | V |
| I_{in} | Input Leakage Current | $V_{in} = 5.5\text{V}$ or GND | 3.6 | | | ±0.1 | | ±1.0 | μA |
| I_{OZ} | Maximum Three-State Leakage Current | $V_{in} = V_{IL}$ or V_{IH} $V_{out} = V_{CC}$ or GND | 3.6 | | | ±0.25 | | ±2.5 | μA |
| I_{CC} | Quiescent Supply Current | $V_{in} = V_{CC}$ or GND | 3.6 | | | 4.0 | | 40.0 | μA |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

MC74LVX125

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0\text{ns}$)

| Symbol | Parameter | Test Conditions | $T_A = 25^\circ\text{C}$ | | | $T_A = -40 \text{ to } 85^\circ\text{C}$ | | Unit |
|----------------------------|--|--|--------------------------|------|------|--|------|------|
| | | | Min | Typ | Max | Min | Max | |
| t_{PLH} , t_{PHL} | Propagation Delay Input to Output | $V_{CC} = 2.7\text{V}$ $C_L = 15\text{pF}$ | | 5.8 | 10.1 | 1.0 | 13.5 | ns |
| | | $C_L = 50\text{pF}$ | | 8.3 | 13.6 | 1.0 | 17.0 | |
| | | $V_{CC} = 3.3 \pm 0.3\text{V}$ $C_L = 15\text{pF}$ | | 4.4 | 6.2 | 1.0 | 8.5 | |
| | | $C_L = 50\text{pF}$ | | 6.9 | 9.7 | 1.0 | 12.0 | |
| t_{PZL} , t_{PZH} | Output Enable Time $\overline{\text{OE}}$ to O | $V_{CC} = 2.7\text{V}$ $C_L = 15\text{pF}$ | | 5.3 | 9.3 | 1.0 | 12.5 | ns |
| | | $R_L = 1\text{k}\Omega$ $C_L = 50\text{pF}$ | | 7.8 | 12.8 | 1.0 | 16.0 | |
| | | $V_{CC} = 3.3 \pm 0.3\text{V}$ $C_L = 15\text{pF}$ | | 4.0 | 5.6 | 1.0 | 7.5 | |
| | | $R_L = 1\text{k}\Omega$ $C_L = 50\text{pF}$ | | 6.5 | 9.1 | 1.0 | 11.0 | |
| t_{PLZ} , t_{PHZ} | Output Disable Time $\overline{\text{OE}}$ to O | $V_{CC} = 2.7\text{V}$ $C_L = 50\text{pF}$ | | 10.0 | 15.7 | 1.0 | 19.0 | ns |
| | | $R_L = 1\text{k}\Omega$ | | | | | | |
| | | $V_{CC} = 3.3 \pm 0.3\text{V}$ $C_L = 50\text{pF}$ | | 8.3 | 11.2 | 1.0 | 13.0 | |
| | | $R_L = 1\text{k}\Omega$ | | | | | | |
| t_{OSHL} , t_{OSLH} | Output-to-Output Skew (Note 1) | $V_{CC} = 2.7\text{V}$ $C_L = 50\text{pF}$ | | | 1.5 | | 1.5 | ns |
| | | $V_{CC} = 3.3 \pm 0.3\text{V}$ $C_L = 50\text{pF}$ | | | 1.5 | | 1.5 | |

1. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

CAPACITIVE CHARACTERISTICS

| Symbol | Parameter | $T_A = 25^\circ\text{C}$ | | | $T_A = -40 \text{ to } 85^\circ\text{C}$ | | Unit |
|-----------|--|--------------------------|-----|-----|--|-----|------|
| | | Min | Typ | Max | Min | Max | |
| C_{in} | Input Capacitance | | 4 | 10 | | 10 | pF |
| C_{out} | Maximum Three-State Output Capacitance | | 6 | | | | pF |
| C_{PD} | Power Dissipation Capacitance (Note 2) | | 14 | | | | pF |

2. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}/4$ (per bit). C_{PD} is used to determine the no-load dynamic power consumption; $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

NOISE CHARACTERISTICS (Input $t_r = t_f = 3.0\text{ns}$, $C_L = 50\text{pF}$, $V_{CC} = 3.3\text{V}$, Measured in SOIC Package)

| Symbol | Characteristic | $T_A = 25^\circ\text{C}$ | | Unit |
|-----------|--|--------------------------|------|------|
| | | Typ | Max | |
| V_{OLP} | Quiet Output Maximum Dynamic V_{OL} | 0.3 | 0.5 | V |
| V_{OLV} | Quiet Output Minimum Dynamic V_{OL} | -0.3 | -0.5 | V |
| V_{IHD} | Minimum High Level Dynamic Input Voltage | | 2.0 | V |
| V_{ILD} | Maximum Low Level Dynamic Input Voltage | | 0.8 | V |

MC74LVX125

SWITCHING WAVEFORMS

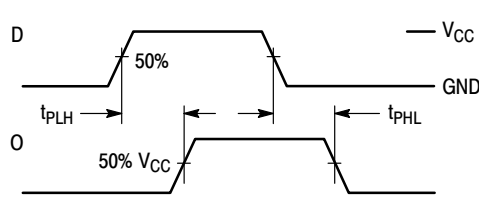


Figure 2.

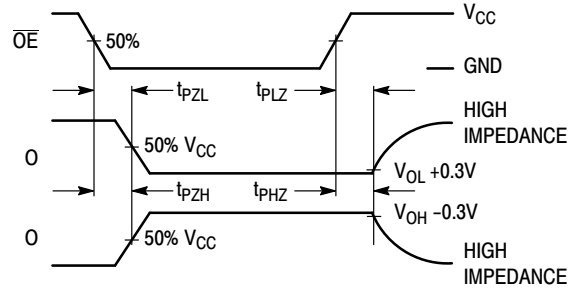
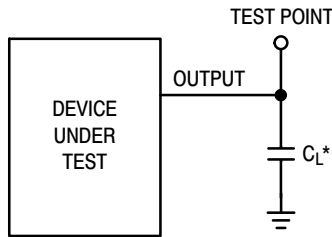


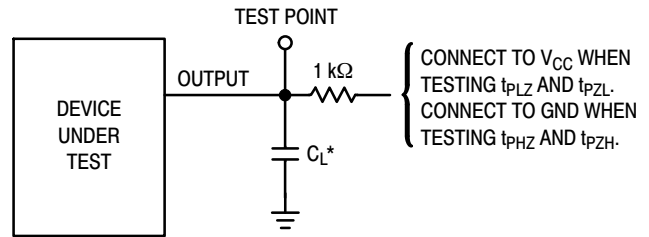
Figure 3.

TEST CIRCUITS



*Includes all probe and jig capacitance

Figure 4. Propagation Delay Test Circuit



*Includes all probe and jig capacitance

Figure 5. Three-State Test Circuit

ORDERING INFORMATION

| Device | Package | Shipping† |
|-----------------|----------------------|------------------|
| MC74LVX125DG | SOIC-14 NB (Pb-Free) | 55 Units / Rail |
| MC74LVX125DR2G | SOIC-14 NB (Pb-Free) | 2500 Tape & Reel |
| MC74LVX125DTG | TSSOP-14 (Pb-Free) | 96 Units / Rail |
| MC74LVX125DTR2G | TSSOP-14 (Pb-Free) | 2500 Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

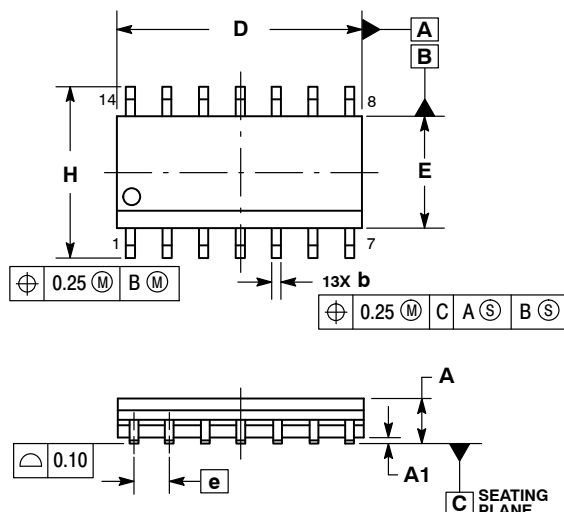
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-14 NB
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

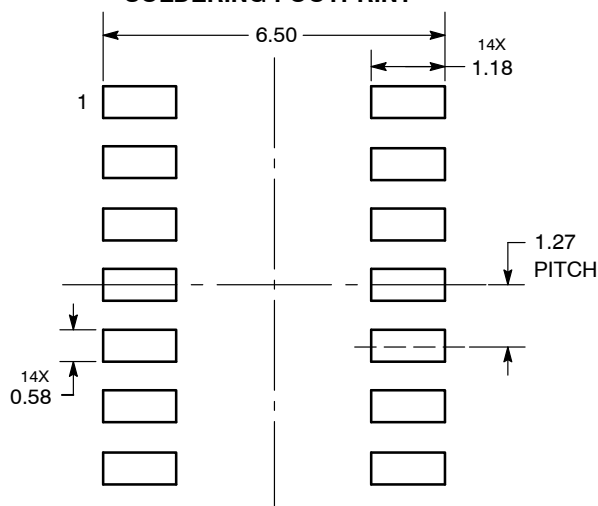


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.35 | 1.75 | 0.054 | 0.068 |
| A1 | 0.10 | 0.25 | 0.004 | 0.010 |
| A3 | 0.19 | 0.25 | 0.008 | 0.010 |
| b | 0.35 | 0.49 | 0.014 | 0.019 |
| D | 8.55 | 8.75 | 0.337 | 0.344 |
| E | 3.80 | 4.00 | 0.150 | 0.157 |
| e | 1.27 BSC | | 0.050 BSC | |
| H | 5.80 | 6.20 | 0.228 | 0.244 |
| h | 0.25 | 0.50 | 0.010 | 0.019 |
| L | 0.40 | 1.25 | 0.016 | 0.049 |
| M | 0° | 7° | 0° | 7° |

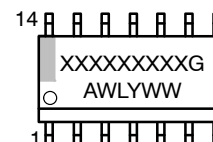
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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SOIC-14
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. NO CONNECTION
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. NO CONNECTION
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 2:
CANCELLED

STYLE 3:
PIN 1. NO CONNECTION
2. ANODE
3. ANODE
4. NO CONNECTION
5. ANODE
6. NO CONNECTION
7. ANODE
8. ANODE
9. ANODE
10. NO CONNECTION
11. ANODE
12. ANODE
13. NO CONNECTION
14. COMMON CATHODE

STYLE 4:
PIN 1. NO CONNECTION
2. CATHODE
3. CATHODE
4. NO CONNECTION
5. CATHODE
6. NO CONNECTION
7. CATHODE
8. CATHODE
9. CATHODE
10. NO CONNECTION
11. CATHODE
12. CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 5:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. NO CONNECTION
7. COMMON ANODE
8. COMMON CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 6:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. ANODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE

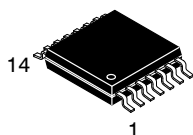
STYLE 7:
PIN 1. ANODE/CATHODE
2. COMMON ANODE
3. COMMON CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. ANODE/CATHODE
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. COMMON CATHODE
12. COMMON ANODE
13. ANODE/CATHODE
14. ANODE/CATHODE

STYLE 8:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. ANODE/CATHODE
7. COMMON ANODE
8. COMMON ANODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. NO CONNECTION
12. ANODE/CATHODE
13. ANODE/CATHODE
14. COMMON CATHODE

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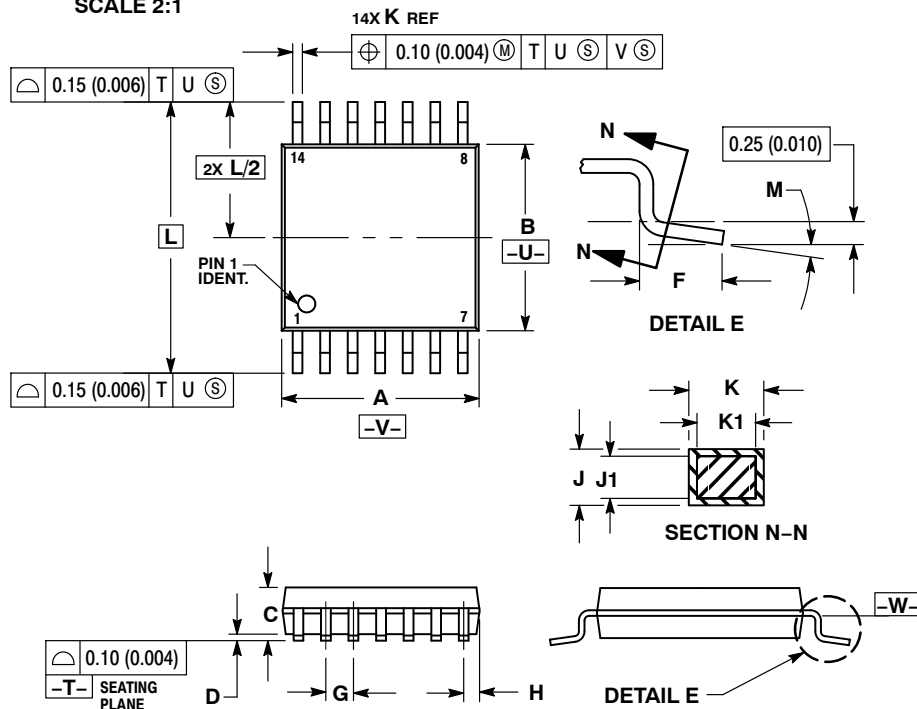
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



TSSOP-14 WB
CASE 948G
ISSUE C

DATE 17 FEB 2016

SCALE 2:1

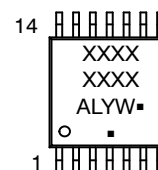


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.90 | 5.10 | 0.193 | 0.200 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | --- | 1.20 | --- | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.50 | 0.60 | 0.020 | 0.024 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

GENERIC MARKING DIAGRAM*

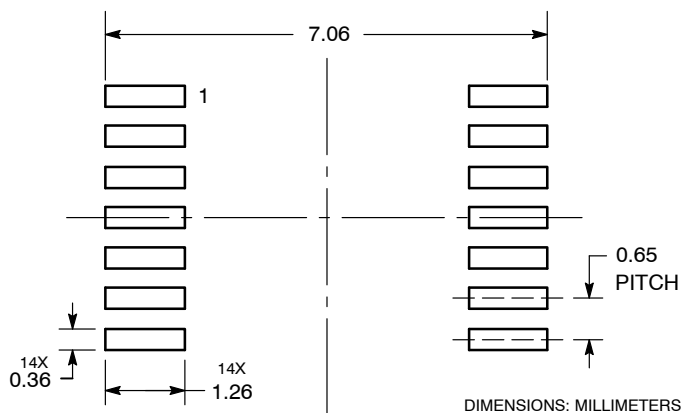


- A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION: TSSOP-14 WB

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